



Micro Commercial Components
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ES1DSR

Features

- For Surface Mount Applications
- Extremely Low Thermal Resistance
- Easy Pick And Place
- High Temp Soldering: 250°C for 10 Seconds At Terminals
- Superfast Recovery Times For High Efficiency

Maximum Ratings

- Operating Temperature: -50°C to +150°C
- Storage Temperature: -50°C to +150°C
- Maximum Thermal Resistance; 15°C/W Junction To Lead

MCC Catalog Number	Device Marking	Maximum Recurrent Peak Reverse Voltage	Maximum RMS Voltage	Maximum DC Blocking Voltage
ES1DSR	ES1D	200V	140V	200V

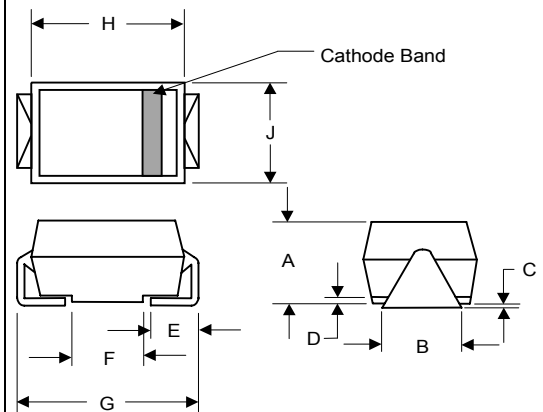
Electrical Characteristics @ 25°C Unless Otherwise Specified

Average Forward Current	$I_{F(AV)}$	1.0A	$T_J = 75^\circ\text{C}$
Peak Forward Surge Current	I_{FSM}	30A	8.3ms, half sine
Maximum Instantaneous Forward Voltage	V_F	.97V	$I_{FM} = 1.0\text{A};$ $T_J = 25^\circ\text{C}^*$
Maximum DC Reverse Current At Rated DC Blocking Voltage	I_R	5 μA 30 μA	$T_J = 25^\circ\text{C}$ $T_J = 125^\circ\text{C}$
Maximum Reverse Recovery Time	T_{rr}	50ns	$I_F=0.5\text{A}, I_R=1.0\text{A},$ $I_{rr}=0.25\text{A}$
Typical Junction Capacitance	C_J	45pF	Measured at 1.0MHz, $V_R=4.0\text{V}$

*Pulse test: Pulse width 200 μsec , Duty cycle 2%

1 Amp Soft Recovery Rectifier 200 Volts

DO-214AC (SMAJ) (High Profile)



DIM	INCHES		MM		NOTE
	MIN	MAX	MIN	MAX	
A	.078	.116	1.98	2.95	
B	.067	.089	1.70	2.25	
C	.002	.008	.05	.20	
D	—	.02	—	.51	
E	.035	.055	.89	1.40	
F	.065	.096	1.65	2.45	
G	.205	.224	5.21	5.69	
H	.160	.180	4.06	4.57	
J	.100	.112	2.57	2.84	

SUGGESTED SOLDER PAD LAYOUT

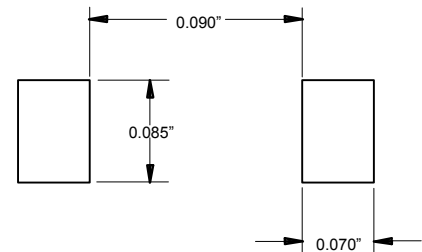
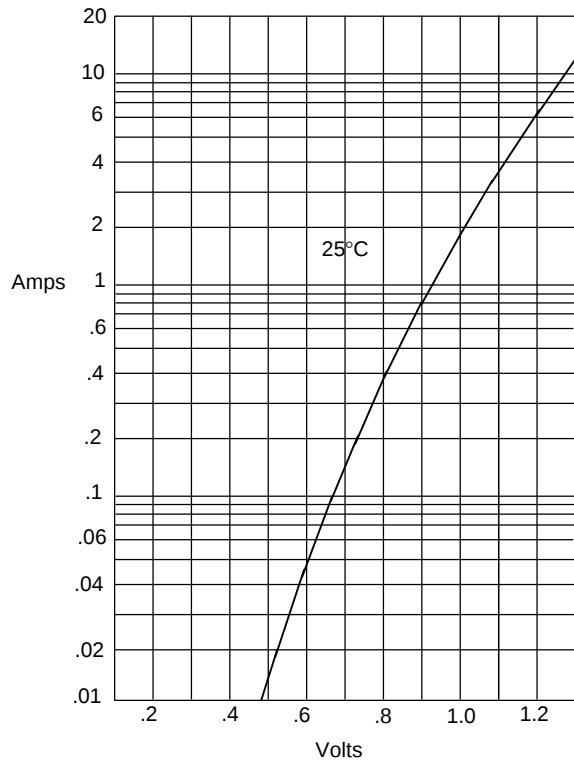
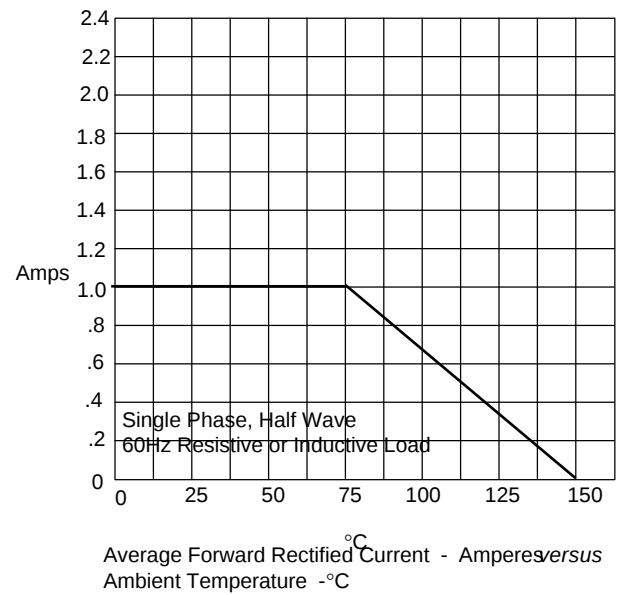


Figure 1
Typical Forward Characteristics



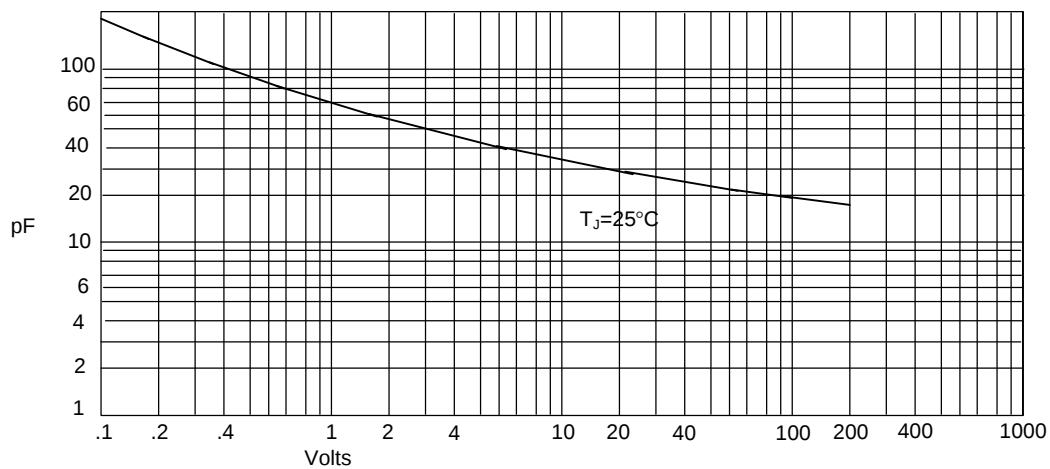
Instantaneous Forward Current - Amperes versus
Instantaneous Forward Voltage - Volts

Figure 2
Forward Derating Curve



Average Forward Rectified Current - Amperes versus
Ambient Temperature - °C

Figure 3
Junction Capacitance



Junction Capacitance - pF versus
Reverse Voltage - Volts

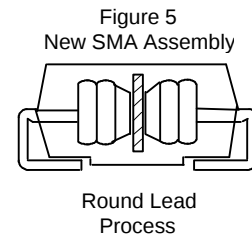
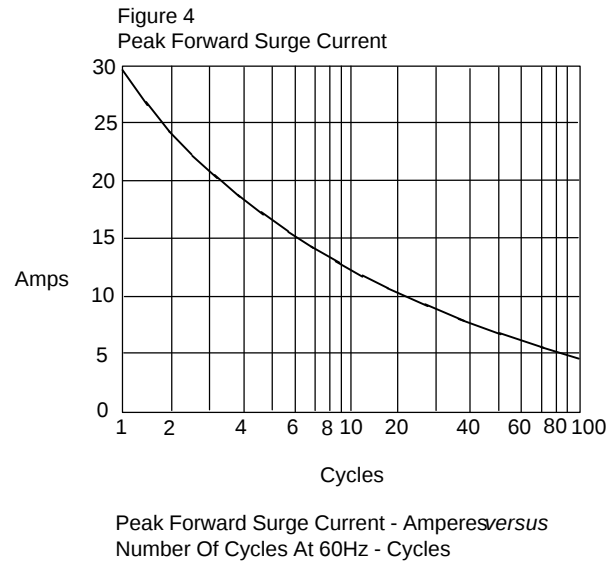
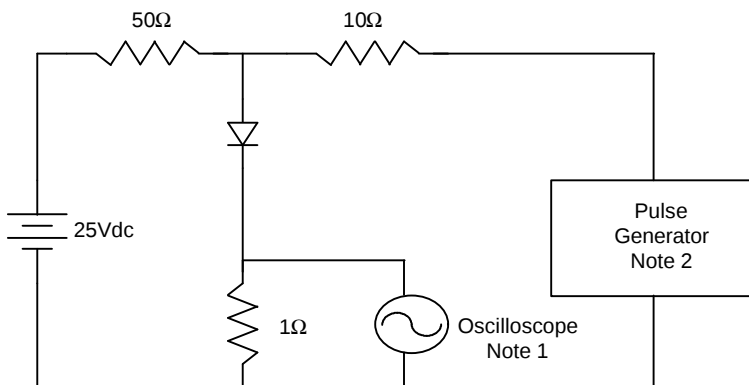


Figure 6
Reverse Recovery Time Characteristic And Test Circuit Diagram



Notes:

1. Rise Time = 7ns max.
Input impedance = 1 megohm, 22pF
2. Rise Time = 10ns max.
Source impedance = 50 ohms
3. Resistors are non-inductive

